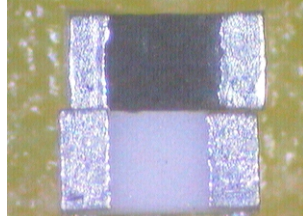


MATERIAL DECLARATION SHEET



Material Number	CR0402-LF			
Product Line	Chip Resistor			
Compliance Date	2010/08/16			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	0.00043	Aluminum oxide	1344-28-1	96%	80.02%	83.35%
				Silicon dioxide	14808-60-7	4%	3.33%	
2	Conductor Layer	Conductor glass	0.000012	Silver	7440-22-4	96%	2.00%	2.10%
				Bismuth trioxide	1304-76-3	1%	0.0275%	
				Barium oxide	1304-28-5	1%	0.0275%	
				Silicon dioxide	7631-86-9	1%	0.0275%	
				Boron oxide	1303-86-2	1%	0.0275%	
3	Resistive Element	Resistor glass	0.000008	Ruthenium dioxide	12036-10-1	25%	0.41%	1.64%
				Silver	7440-22-4	40%	0.66%	
				Palladium	7440-05-3	15%	0.25%	
				Lead oxide glass	1317-36-8	20%	0.33%	
4	Over-Coating	Epoxy	0.00001	Epoxy	29690-82-2	100%	2.03%	2.03%
5	End Terminal	Nickel Chromium	0.000002	Nickel	7440-02-0	80%	0.29%	0.36%
				Chromium III	7440-47-3	20%	0.07%	
6	Ni Plating	Nickel	0.00003	Nickel	7440-02-0	100%	5.56%	5.56%
7	Sn Plating	Tin	0.00002	Tin	7440-31-5	100%	4.96%	4.96%
			Total weight	0.000512				

This Document was updated on: 05.18.2010

MATERIAL DECLARATION SHEET

BOURNS[®]

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemption 5 – lead in ... glass ... of electronic components.